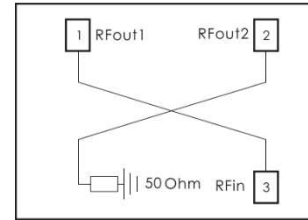


Performance

- Frequency: 6-18GHz
- Insertion loss: 0.9dB
- Chip size: 2.0*1.8*0.1mm

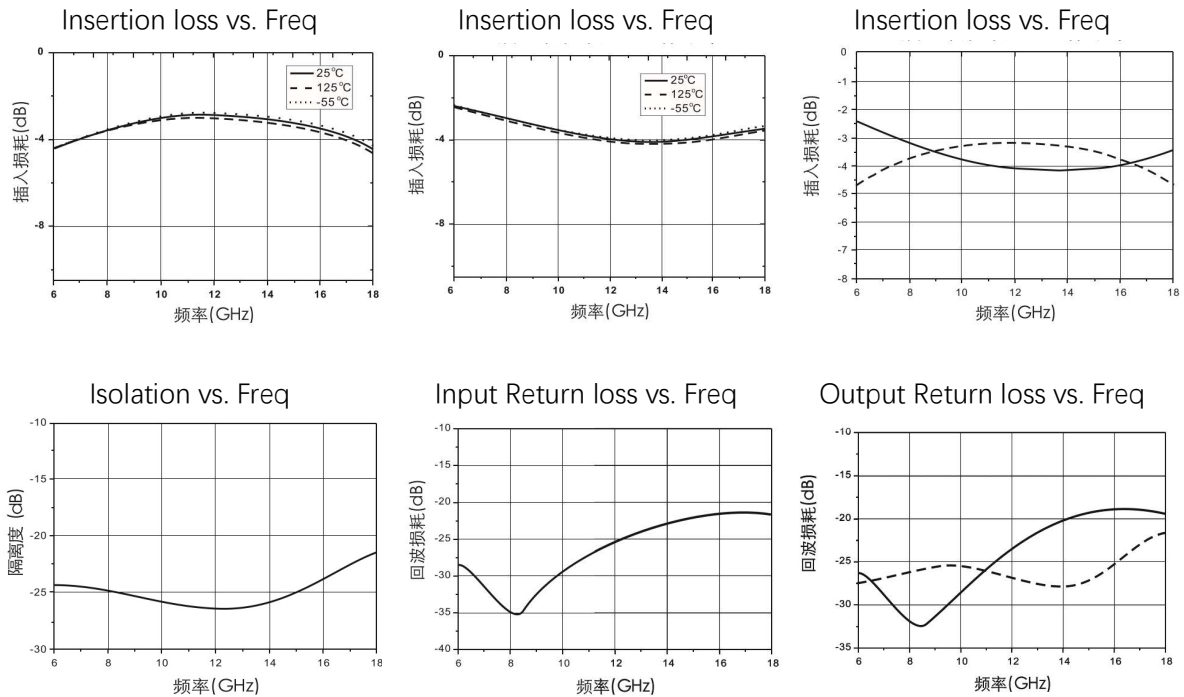
Function Diagram



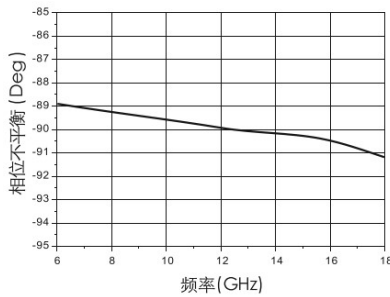
Electrical Specifications (Ta=+25°C, 50Ω system)

Parameter	Min	Typical	Max	Unit
Frequency Range	6-18			GHz
Insertion Loss	-	0.9	-	dB
Input Return loss	18	22	-	dB
Output Return loss	17	25	-	dB
Isolation	18	25	-	dB
Amplitude Balance	-	±1	-	dB
Phase Balance	-	±2.0	-	Deg

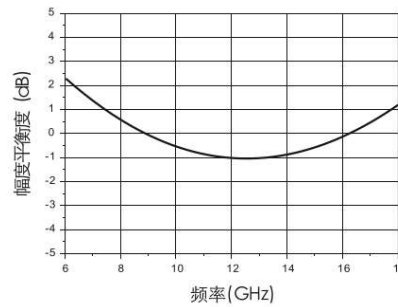
Test Curves (Die chip + Bonding line test)



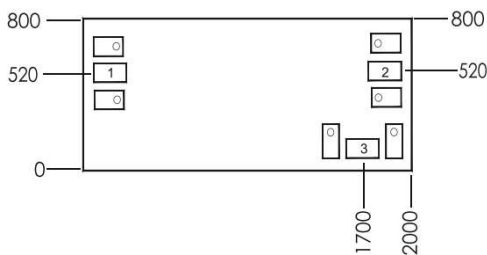
Phase Balance vs. Freq



Amplitude Balance vs. Freq



Outline Size



Note:

Unit: um

1. Bottom side is gold plated
2. Bottom side is GND
3. Bonding pads is gold plated, size: 200*100(um)
4. Don't bonding on thru holds
5. Tolerance: ±50um

Bonding Pads Definition

Number	Symbol	Description
1,2	RFout 1, RFout2	RF output port, 50ohm
3	RFin	RF input port, 50 ohm
-	GND	Bottom must be GND

Absolute Max Ratings

Max Input Power	+27dBm
Static Class	Class 1A
Storage Temperature	-65 ~ +150°C
Operating Temperature	-55 ~ +125°C

Note: For high power application, assemble with Eutectic sintering.

Application

